

PROCESS FOR JOINING TWO SEMICONDUCTOR SUBSTRATES

ABSTRACT

5 The invention relates to a process for joining two semiconductor
substrates by molecular adhesion comprising: a step a) of
bringing a first and a second (2) substrate into intimate contact
in order to form an assembly exhibiting a bonding interface (4);
a step b) of reaction-annealing the bonding interface (4) at a
10 first temperature, higher than a predetermined first
temperature, this step b) generating bubbles at the joining
interface; a step c) of at least partially debonding the two
substrates at the bonding interface (4) in order to eliminate
the bubbles; a step d) of bringing the first and the second (2)
15 substrate back into intimate contact at the bonding interface
(4) in order to reform the assembly.

Figure to be published with the abstract: Fig. 1